

HC1503

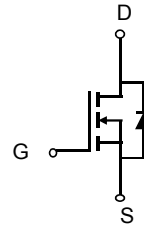
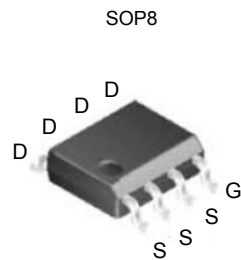
30V N-Channel MOSFET

General Description

The HC1503 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.

Features

V_{DS}	30V
I_D (at $V_{GS}=10V$)	13A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	15m Ω (Max)
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	20m Ω (Max)



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	30	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Drain Current-Continuous	TC=25 $^\circ\text{C}$	I_D	13	A
	TC=100 $^\circ\text{C}$	I_D	10	A
Drain Current – Pulsed	I_{DM}	52	A	
Maximum Power Dissipation	P_D	2.1	W	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ\text{C}$	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		7	$^\circ\text{C}/\text{W}$
Thermal Resistance unction-to-Ambient	$R_{\theta JA}$		62	$^\circ\text{C}/\text{W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.6	1.0	1.5	V
R _{DS(ON)}	Drain-Source On-State esistance	V _{GS} =10V, I _D =10A		12	15	mΩ
		V _{GS} =4.5V, I _D =5A		14	20	mΩ
DYNAMIC PARAMETERS						
C _{ISS}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1.0MHz		620		pF
C _{OSS}	Output Capacitance			85		pF
C _{RSS}	Reverse Transfer Capacitance			60		pF
SWITCHING PARAMETERS						
t _{d(on)}	Turn-on Delay Time	V _{GS} =10V V _{DS} =15V R _L =2.6Ω R _{GEN} =3Ω		2.6		nS
t _r	Turn-on Rise Time			8.5		nS
t _{d(off)}	Turn-Off Delay Time			18		nS
t _f	Turn-Off Fall Time			5		nS
Q _g	Total Gate Charge	V _{DS} =15V, I _D =3A, V _{GS} =4.5V		7.1		nC
Q _{gs}	Gate-Source Charge			1.4		nC
Q _{gd}	Gate-Drain Charge			1.5		nC
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _{SD} =1A		0.72	1.3	V
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		2		Ω

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%.
3. Essentially independent of operating temperature.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

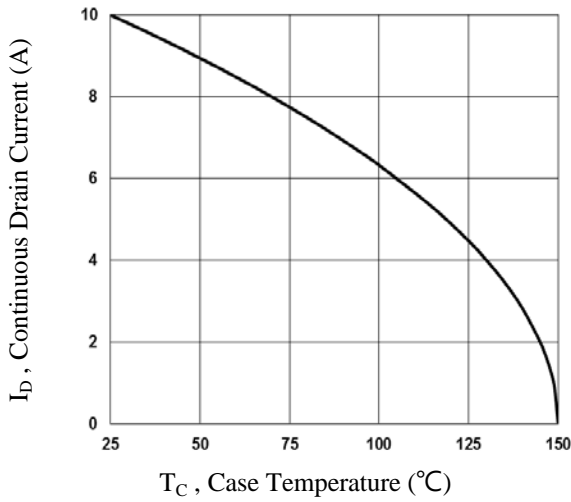


Fig.1 Continuous Drain Current vs. T_C

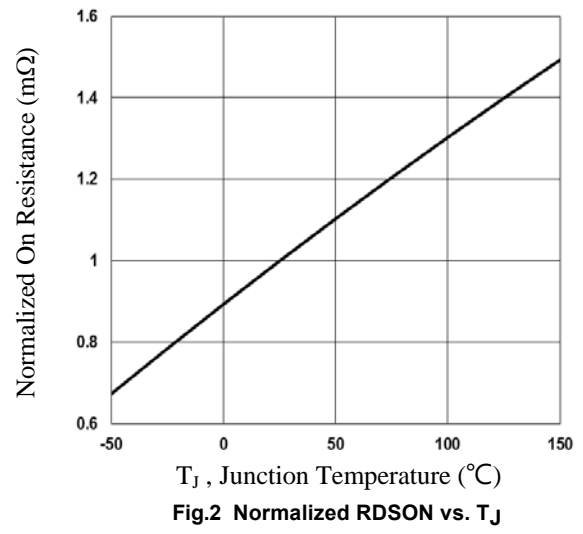


Fig.2 Normalized R_{DSON} vs. T_J

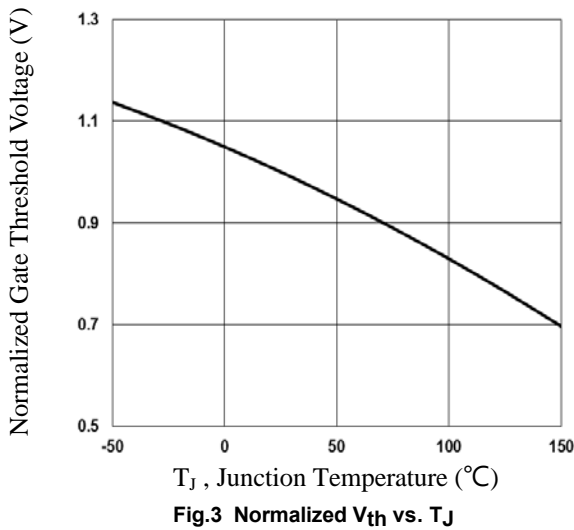


Fig.3 Normalized V_{th} vs. T_J

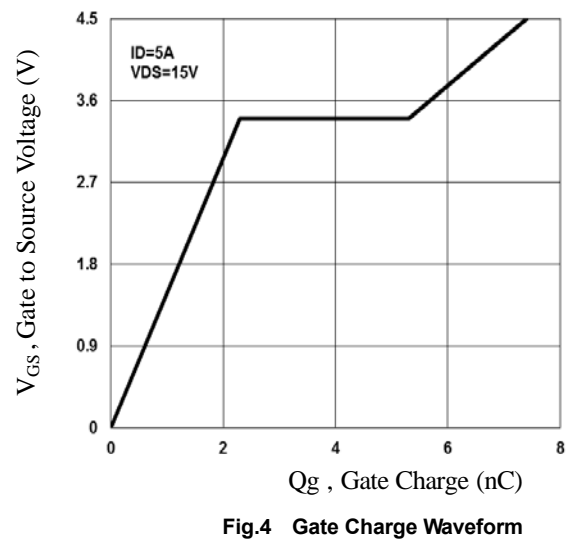


Fig.4 Gate Charge Waveform

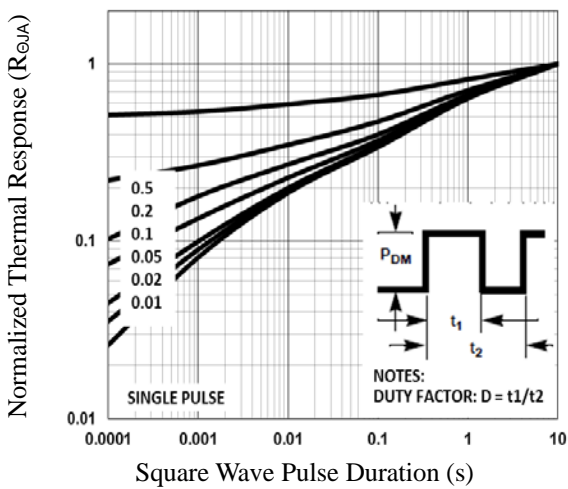


Fig.5 Normalized Transient Response

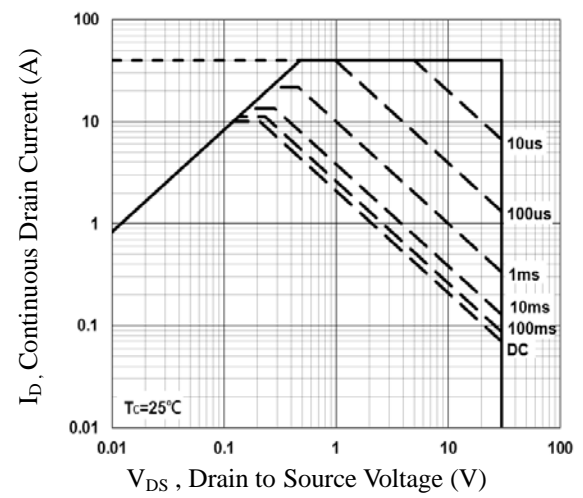


Fig.6 Maximum Safe Operation Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

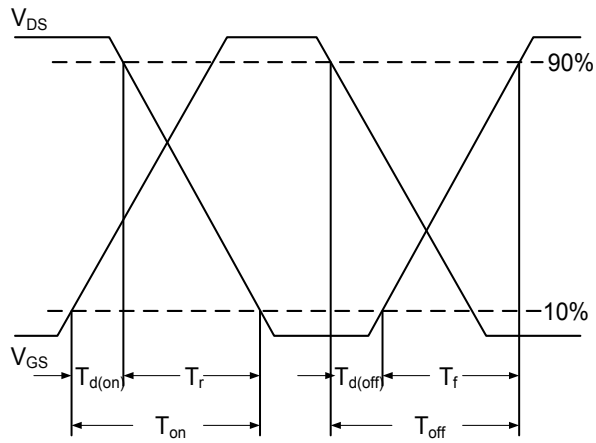


Fig.7 Switching Time Waveform

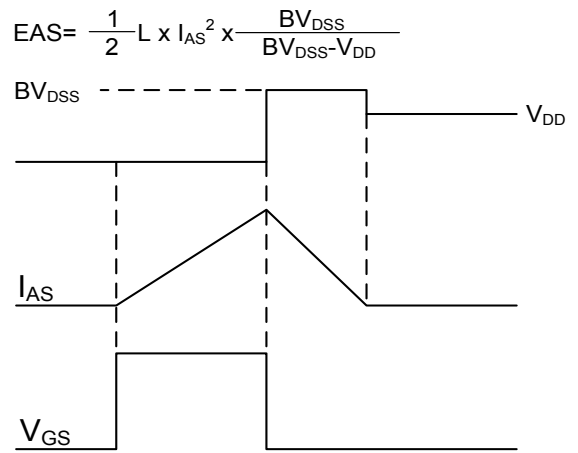
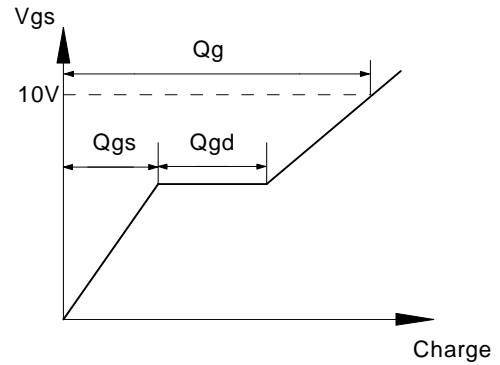
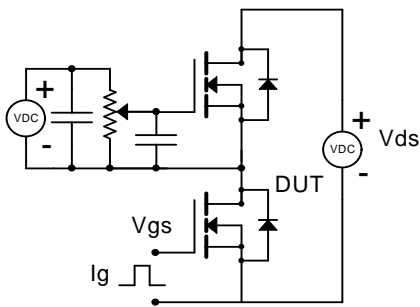
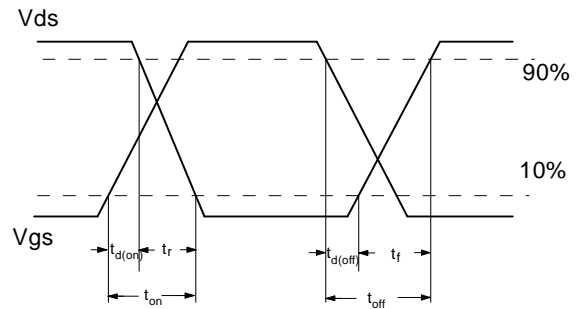
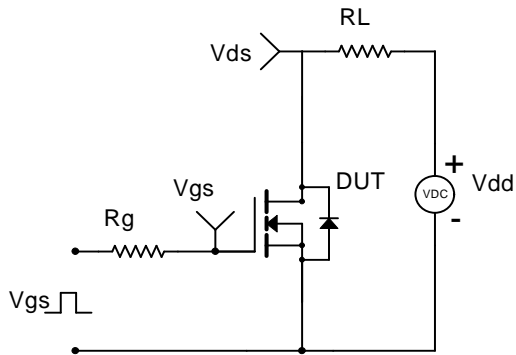


Fig.8 EAS Waveform

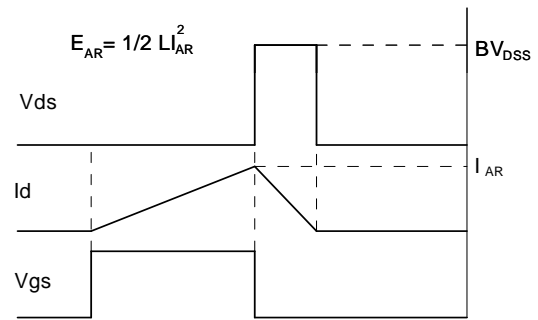
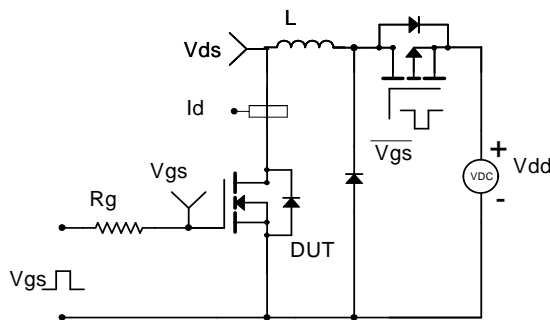
Gate Charge Test Circuit & Waveform



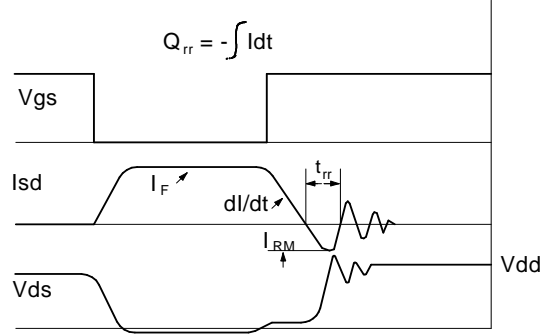
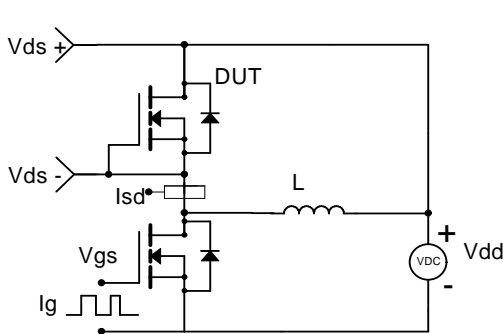
Resistive Switching Test Circuit & Waveforms



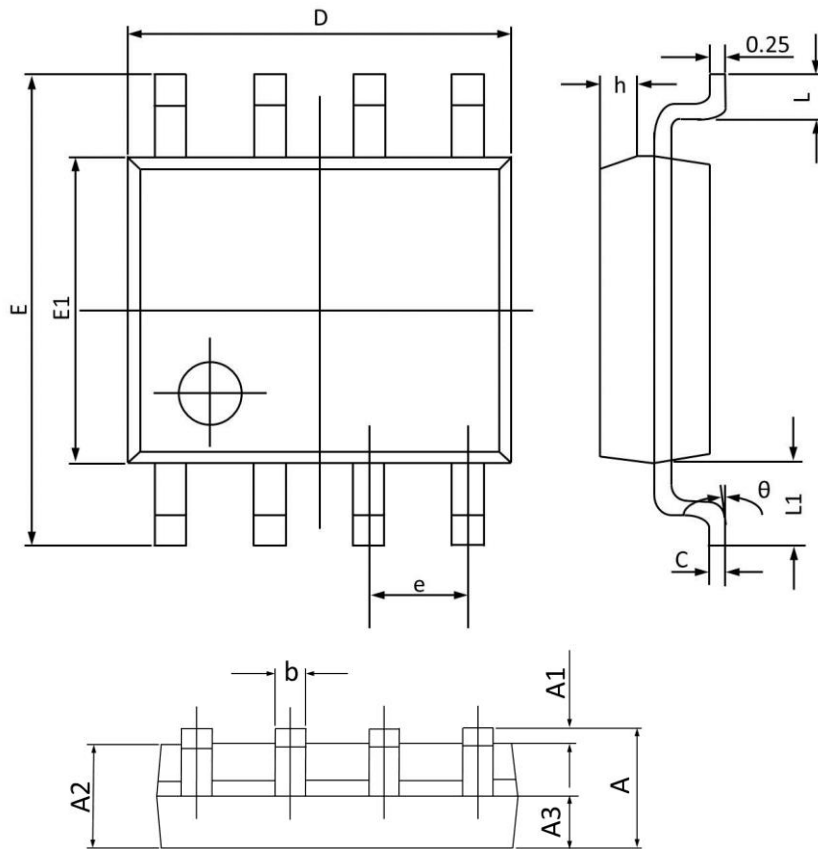
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°